

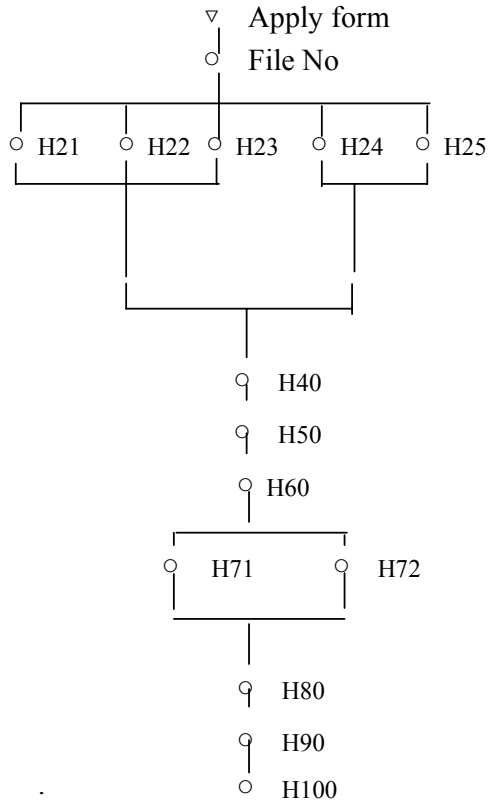
The procedure of Hi-Rel Exp.	QM	OP	OI	II	SPEC	OTS	File No:
		✓					V-Q A 1007

5.1 Testing item and condition:

Item	Testing item	Condition	Ref. Doc.
1	STEAM AGING TEST SOLDER ABILITY	230°C±5°C FOR 5±0.5SEC OR 7±0.5SEC	MIL-STD-202F METHOD-208
2	HIGH TEMPERATURE REVERSE BIAS TEST	Ta=100°C±5°C/125°C±5°C VR=80% RATED VR 1000HRS/96HRS	MIL-STD-750C METHOD-1026
3	THERMAL FATIGUE	ON: 300SECS OFF: 300SECS 1000 cycles/300cycles	MIL-STD-750C METHOD-1036
4	PRESSURE COOKER LIFE TEST	15 PSIG TA=121°C 8HRS	
5	HIGH TEMPERATURE STORAGE LIFE	150°C±5°C/ 1000HRS /96HRS	MIL-STD-750C METHOD - 1031
6	SOLDER RESISTANCE	260±5°C FOR 10±2SEC	MIL-STD-750C METHOD-2031
7	THERMAL SHOCK	0°C±5°C/5MIN AND 100±5°C/5MIN TOTAL 10 CYCLES	MIL-STD-750C METHOD-1056
8	TEMPERATURE CYCLING	-55±5°C/30MIN AND 125±5°C/30MIN TOTAL 10 CYCLES	MIL-STD-750C METHOD-1051
9	HUMIDITY	TA=65±5°C, RH=98±10% 1000HRS/168HRS	MIL-STD-202F METHOD-103B

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		✓					V-Q A 1 0 0 7

5.5 Procedure:



- H21: New product
- H22: Engineering change
- H23: Benchmarking or customer request
- H24: BURN IN
- H25: Random Lot Screening
- H40: GROUP A TEST
- H50: GROUP B/C TEST (Env. Testing)
- H60: Analysis
- H71: Go On testing
- H72: Stop testing
- H80: Report
- H90: FA
- H100: Follow up